COMPLIANT

HALOGEN

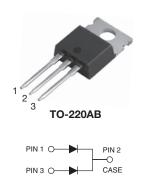
FREE



Vishay General Semiconductor

Dual High Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

Ultra Low $V_F = 0.33 \text{ V}$ at $I_F = 5.0 \text{ A}$



| PRIMARY CHARACTERISTICS | | | | | | | |
|--|----------------|--|--|--|--|--|--|
| $I_{F(AV)}$ | 2 x 30 A | | | | | | |
| V_{RRM} | 60 V | | | | | | |
| I _{FSM} | 300 A | | | | | | |
| V_F at $I_F = 30 \text{ A} (T_J = 125 ^{\circ}\text{C})$ | 0.55 V | | | | | | |
| T _J max. | 175 °C | | | | | | |
| Package | TO-220AB | | | | | | |
| Circuit configuration | Common cathode | | | | | | |

FEATURES

- Trench MOS Schottky technology
- · Low forward voltage drop, low power losses
- · High efficiency operation
- Solder bath temperature 275 °C maximum, 10 s per JESD 22-B106
- AEC-Q101 qualified available:
 - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

MECHANICAL DATA

Case: TO-220AB

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test, HM3 suffix

meets JESD 201 class 2 whisker test

Mounting torque: 10 in-lbs maximum

| MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted) | | | | | | | | |
|--|-------------------------------|--------------------|------|-----|--|--|--|--|
| PARAMETER | SYMBOL | VX60M60C | UNIT | | | | | |
| Maximum repetitive peak reverse voltage | | V _{RRM} | 60 | V | | | | |
| Maximum average forward rectified current (fig. 1) | per device | | 60 | | | | | |
| | per diode | I _{F(AV)} | 30 | _ A | | | | |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | | I _{FSM} | 300 | А | | | | |
| Operating junction temperature range | T _J ⁽¹⁾ | -40 to +175 | °C | | | | | |
| Storage temperature range | T _{STG} | -40 to +175 | 7 | | | | | |

Note

 $^{(1)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$



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| ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted) | | | | | | | | |
|---|-----------------------|-------------------------|-------------------------------|------|------|------|--|--|
| PARAMETER | TEST CO | NDITIONS | SYMBOL | TYP. | MAX. | UNIT | | |
| Instantaneous forward voltage per diode | I _F = 5 A | | V _F ⁽¹⁾ | 0.45 | - | V | | |
| | I _F = 15 A | $T_J = 25 ^{\circ}C$ | | 0.52 | - | | | |
| | I _F = 30 A | | | 0.60 | 0.66 | | | |
| | I _F = 5 A | | | 0.33 | - | | | |
| | I _F = 15 A | T _J = 125 °C | | 0.44 | - | | | |
| | I _F = 30 A | | | 0.55 | 0.60 | | | |
| Reverse current at rated V _R per diode | V _B = 60 V | T _J = 25 °C | I _R ⁽²⁾ | - | 0.6 | mA | | |
| | v _R = 60 v | T _J = 125 °C | 'R (=) | 9 | 40 | | | |
| Typical junction capacitance | 4.0 V, 1 MHz | | CJ | 3800 | - | pF | | |

Notes

 $^{(1)}$ Pulse test: 300 μs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width $\leq 5 \text{ ms}$

| THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted) | | | | | | |
|---|-----------------------|----------|------|--|--|--|
| PARAMETER | SYMBOL | VX60M60C | UNIT | | | |
| Typical thermal resistance per device | R ₀ JC (1) | 1 | °C/W | | | |

Note

(1) Thermal resistance junction-to-case to follow JEDEC® 51-14 transient dual interface test method (TDIM)

| ORDERING INFORMATION (Example) | | | | | | | |
|--------------------------------|-----------------|--------------|---------------|---------------|--|--|--|
| PREFERRED P/N | UNIT WEIGHT (g) | PACKAGE CODE | BASE QUANTITY | DELIVERY MODE | | | |
| VX60M60C-M3/P | 2.04 | Р | 50/tube | Tube | | | |
| VX60M60CHM3/P (1) | 2.04 | Р | 50/tube | Tube | | | |

Note

(1) AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

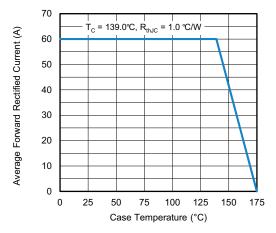


Fig. 1 - Maximum Forward Current Derating Curve

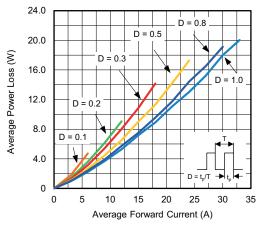


Fig. 2 - Average Power Loss Characteristics

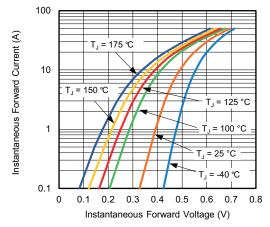


Fig. 3 - Typical Instantaneous Forward Characteristics

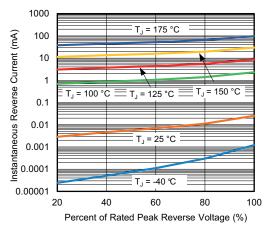


Fig. 4 - Typical Reverse Leakage Characteristics

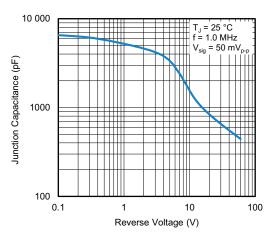


Fig. 5 - Typical Junction Capacitance

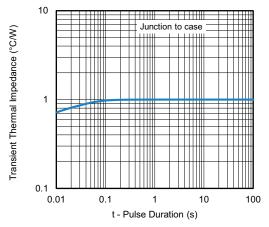
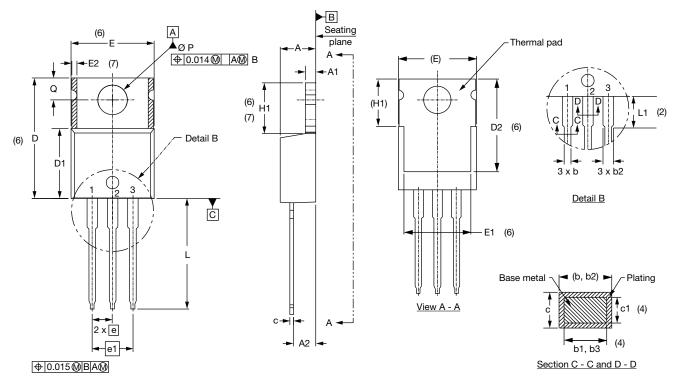
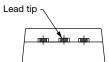


Fig. 6 - Typical Transient Thermal Impedance

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DIMENSIONS in millimeters (inches) **TO-220AB**





Conforms to JEDEC® outline TO-220AB

| SYMBOL | MILLIM | IETERS | INC | HES | NOTES | NOTES | NOTES | | SYMBOL | MILLIMETERS | | INCHES | | NOTES |
|----------|--------|--------|-------|-------|-------|-------|----------|-------|--------|-------------|-------|--------|--|-------|
| STINIBUL | MIN. | MAX. | MIN. | MAX. | NOTES | | STIVIDOL | MIN. | MAX. | MIN. | MAX. | | | |
| Α | 4.25 | 4.65 | 0.167 | 0.183 | | | D2 | 11.68 | 12.88 | 0.460 | 0.507 | 6 | | |
| A1 | 1.14 | 1.40 | 0.045 | 0.055 | | | Е | 10.11 | 10.51 | 0.398 | 0.414 | 3, 6 | | |
| A2 | 2.56 | 2.92 | 0.101 | 0.115 | | | E1 | 6.86 | 8.89 | 0.270 | 0.350 | 6 | | |
| b | 0.69 | 1.01 | 0.027 | 0.040 | | | E2 | ı | 0.76 | ı | 0.030 | 7 | | |
| b1 | 0.38 | 0.97 | 0.015 | 0.038 | 4 | | е | 2.41 | 2.67 | 0.095 | 0.105 | | | |
| b2 | 1.20 | 1.73 | 0.047 | 0.068 | | | e1 | 4.88 | 5.28 | 0.192 | 0.208 | | | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 | | H1 | 5.84 | 6.86 | 0.230 | 0.270 | 6, 7 | | |
| С | 0.36 | 0.61 | 0.014 | 0.024 | | | L | 13.52 | 14.02 | 0.532 | 0.552 | | | |
| c1 | 0.36 | 0.56 | 0.014 | 0.022 | 4 | | L1 | 3.32 | 3.82 | 0.131 | 0.150 | 2 | | |
| D | 14.85 | 15.25 | 0.585 | 0.600 | 3 | | ØΡ | 3.54 | 3.73 | 0.139 | 0.147 | | | |
| D1 | 8.38 | 9.02 | 0.330 | 0.355 | | | Q | 2.60 | 3.00 | 0.102 | 0.118 | | | |

Notes

- ⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimensions E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC® TO-220, except A2 (maximum) and D2 (minimum) where dimensions are derived from the actual package outline



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